



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2020-09-23
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	giovanni giacopello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SMB15F58AY	AH6Y*YFU068I	A	64BA	2020-09-23
	Amount	UoM	Unit type	ST ECOPACK Grade
	60	mg	Each	ECOPACK 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM00392114	



Package Designator	Size	Nbr of instances	Shape	
CHP	4.30,3.75,0.98	2	flat	
Comment	SMB Flat NEP			

QueryList : RoHS Directive 2011/65/EU-July 2011 Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2020/363_ March 2020	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.05	die	783
Lead	2.04	soft solder	34067

QueryList : REACH-25th June 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	2.04	Soft solder	34067
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	2.044	Soft solder	920306

Responsible metals sourcing	
Query	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Gold, Tin,
This product is in the scope of the responsible metals sourcing, its compliance is covered by our company processes .	

Material Composition Declaration :						Mfr Item Name	AH6Y*YFU068I					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	3.740	mg	supplier	die	Silicon(Si)	7440-21-3		3.523	mg	941979	58718
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.043	mg	11497	717
				supplier	metallisation	Gold(Au)	7440-57-5		0.024	mg	6417	400
				supplier	metallisation	Nicke(Ni)	7440-02-0		0.047	mg	12567	783
				supplier	passivation	Silicon oxide	7631-86-9		0.025	mg	6684	417
Leadframe	M-004 Copper and its alloys	23.959	mg	supplier	polymer coating	Durimide	proprietary		0.078	mg	20856	1300
				supplier	alloy & coating	Copper(Cu)	7440-50-8		23.928	mg	998706	398800
				supplier	alloy & coating	Iron(Fe)	7439-89-6		0.012	mg	501	200
Soft solder	Solder	2.221	mg	SVHC	alloy & coating	Iron Phosphide(FeP)	26508-33-8		0.019	mg	793	317
				supplier	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temper	2.044	mg	920306	34067
				supplier	solder	Tin(Sn)	7440-31-5		0.111	mg	49977	1850
				supplier	solder	Silver(Ag)	7440-22-4		0.055	mg	24764	917
Encapsulation	M-011 Other inorganic materials	23.700	mg	supplier	solder	dry flux residue	proprietary		0.011	mg	4953	183
				supplier	mold compound	Amorphous silica	7631-86-9		20.975	mg	885022	349583
				supplier	mold compound	Epoxy Cresol Novolac	29690-82-2		1.422	mg	60000	23700
				supplier	mold compound	Phenolic resin	9003-35-4		1.067	mg	45021	17783
				supplier	mold compound	Carbon black	1333-86-4		0.095	mg	4008	1583
				supplier	mold compound	Magnesium oxide	1309-48-4		0.047	mg	1983	783
connections coating	Solder	0.321	mg	supplier	mold compound	Aluminium hydroxide	21645-51-2		0.047	mg	1983	783
				supplier	mold compound	Mercaptopropyl trimethoxysilane	4420-74-0		0.047	mg	1983	783
Clip		6.059	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.321	mg	1000000	5350
				supplier	alloy	Copper(Cu)	7440-50-8		6.056	mg	999505	100933
				supplier	alloy	Copper Posphorous	12517-41-9		0.003	mg	495	50